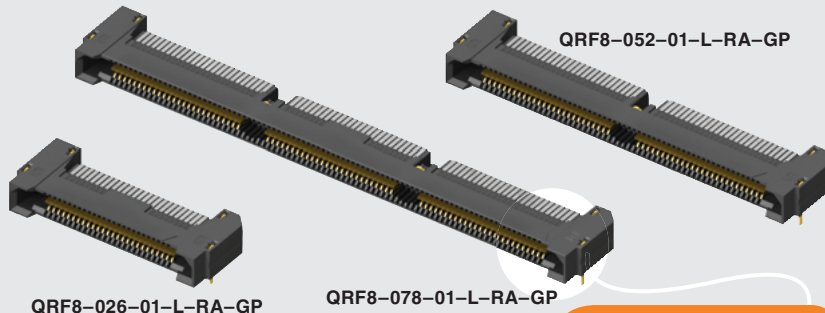




(0,80 mm) .0315"



QRF8-RA SERIES

RIGHT ANGLE GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QRF8-RA

Insulator Material:

Black LCP

Contact Material:

BeCu

Ground Plane Material:

Phosphor Bronze

Plating:

Au or Sn over

50µ" (1,27 µm) Ni

Current Rating (QRF8-RA/QRM8):

Contact:

2.2 A per pin

(1 pin powered per row)

Ground Plane:

8.6 A per ground plane
(1 ground plane powered)

Operating Temp Range:

-55°C to +125°C

Voltage Rating:

230 VAC / 325 VDC

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (026-052)

(0,15 mm) .006" max (078)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings
- Contact Samtec.

Note:
Patented

Note:
For -GP (Guide Post option) to -GP (Guide Post option) mating.

Note:
Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QRM8 (-GP required)



Integral
ground/power
plane

Edge Rate®
contacts

QRM8-RA/QRF8-RA	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
Single-Ended Signaling	4.5 GHz / 9 Gbps	14.5 GHz / 29 Gbps
Differential Pair Signaling	6 GHz / 12 Gbps	16 GHz / 32 Gbps

*Performance data includes effects of a non-optimized PCB.

**Test board losses de-embedded from performance data.

Complete test data available at www.samtec.com?QRM8-RA or contact sig@samtec.com

28⁺
G b p s

Guide
Hole



- Edge Rate® contacts
- Increased contact wipe
- Integral guide post

QRF8 — POSITIONS PER ROW — 01 — PLATING OPTION — RA — GP — OPTION

—026, —052, —078
(52 total positions per bank)

—L
= 10µ" (0,25 µm)
Gold on contact,
Matte Tin on tail

—GP
= Guide Post
(Requires -GP on mating connector)

—K
= (7,00 mm)
.275" DIA
Polyimide film
Pick &
Place Pad
(-052 only)

—TR
= Tape & Reel
(-026, -052 only)

